




<b>PCN Number:</b>	20200424001.1		<b>PCN Date:</b>	Apr 28, 2020	
<b>Title:</b>	Qualification of FFAB as an additional Fab Site option for select BICMOS13 devices				
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>		<b>Dept:</b>	Quality Services	
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Jul 28, 2020		<b>Estimated Sample Availability:</b>	Date provided at sample request.	
<b>Change Type:</b>					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		
<b>PCN Details</b>					
<b>Description of Change:</b>					
Texas Instruments is pleased to announce the qualification of its FFAB fabrication facility as an additional Wafer Fab source for the selected devices listed in "Product Affected" section.					
<b>Current Sites</b>			<b>Additional Sites</b>		
<b>Current Fab Site</b>	<b>Process</b>	<b>Wafer Diameter</b>	<b>Additional Fab Site</b>	<b>Process</b>	<b>Wafer Diameter</b>
MAINEFAB	BICMOS13	200mm	FFAB	BICMOS13	200mm
Qual details are provided in the Qual Data Section.					
<b>Reason for Change:</b>					
Continuity of Supply					
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>					
None					
<b>Changes to product identification resulting from this PCN:</b>					
<b>Current</b>					
Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City		
MAINEFAB	CUA	USA	South Portland		
<b>New Fab Site</b>					
Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City		
FR-BIP-1	TID	DEU	Freising		
Sample product shipping label (not actual product label)					
 MADE IN: Malaysia 2DC: 20:				(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483S12 (P) (2P) REV: (V) 0033317 (20L) CS0: SHE (21L) CCO: USA (22L) AS0: MLA (23L) ACO: MYS	
MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: 39 ITEM: <b>LBL: 5A (L)T0:1750</b>					
<b>Product Affected Group:</b>					
DS280DF810ABVR	DS280DF810ABVT	DS280DF810ABWR	DS280DF810ABWT		

**Qualification Report**  
**Approve Date 22-April-2020**

**Qualification Results**  
**Data Displayed as: Number of lots / Total sample size / Total failed**

Type	Test Name / Condition	Duration	Qual Device: DS280DF810ABWT	QBS Process Device: LMH1297RTVT R	QBS Process Reference LMX2581SQENOPB	QBS Package Reference DS110DF1610SFB
ELFR	Early Life Failure Rate, Ta=115C, Tj~160C	48HRS	-	-	3/2400/0	-
HTOL	Life Test, Ta=115C, Tj~160C	500HRS	-	-	3/231/0	-
HTOL	Life Test, Ta=125C	1000HRS	1/77/0	2/154/0	-	-
AC	Autoclave 121C	96HRS	-	-	3/231/0	-
HAST	Biased HAST, 130C/85%RH	96HRS	-	-	3/231/0	3/231/0
TC	Temperature Cycle, -55/125C	700CYC	-	-	3/231/0	3/231/0
HTSL	High Temp Storage Bake 150C	1000HRS	-	-	3/231/0	3/231/0
HBM	ESD - HBM	2000V	1/3/0	-	3/9/0	-
CDM	ESD - CDM	1000V	1/3/0	-	-	-
LU	Latch-up	25C	1/6/0	-	3/18/0	-
LU	Latch-up	85C	1/6/0	-	3/18/0	-

- QBS: Qual By Similarity

- Qual Device DS280DF810ABWT is qualified at LEVEL3-260CG

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JEDEC47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**

Qualified Pb-Free (SMT) and Green

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